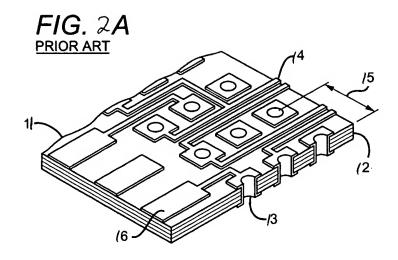


FIGURE 1. PRIOR ART



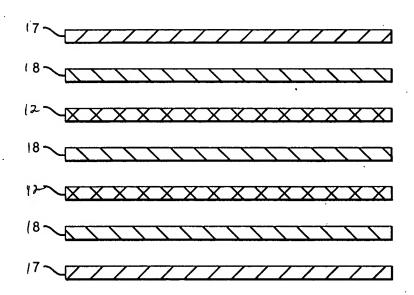


FIG. 2B

1001
Mix resin components and vacuum degas to remove trapped air

1002 Heat resin and pump to slot die

1003
Extrude thin polymer film onto moving web using slot die

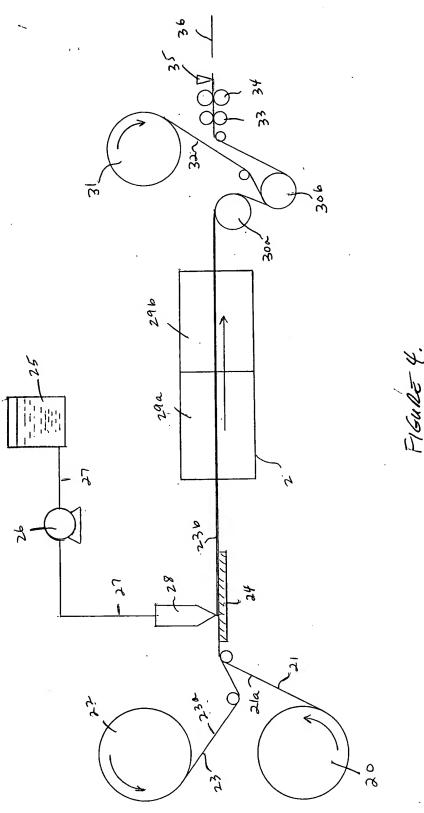
1004 B-stage (partially cure) coating

> 1005 Cool web

1006 Add top release liner

1007 Trim edge to proper width

1008 Cut sheet to proper length



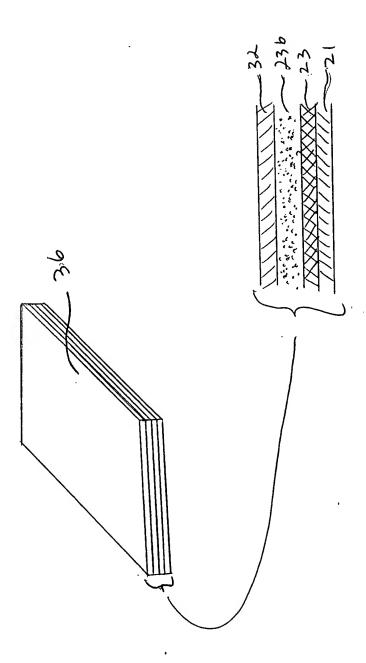


FIGURE 5.

2001

Providing a first core that includes a substrate and heavy copper circuit traces

2002

Stacking coated prepreg sheets between first cores such that the polymer coating is adjacent to heavy copper features

2003

Stacking additional coated prepreg layers and heavy copper circuitized cores to form the desired stack-up

2004

Laminating the plurality of coated prepreg and circuitized cores to form a fully cured multilayer circuit board

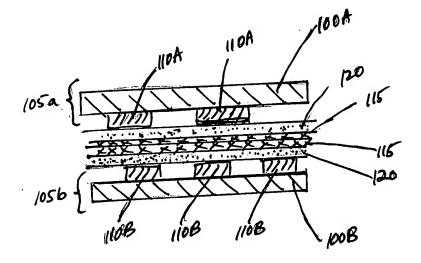


FIGURE 7.

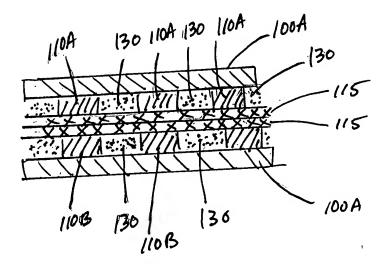


FIGURE 8.